

2023/10

ADEKA REMYLOP FL-388

■ Product Features

- One-component heat curing adhesive
- Electrical conductivity
- Epoxy type (Halogen-free available)
- Rapid curing type
(Induction heating, laser heating possible)

■ Properties (uncured)

Viscosity / 25°C	2 ⁻¹	135	Pa · s
	20 ⁻¹	27	Pa · s
Thixotropic value	2 ⁻¹ /20 ⁻¹	5.0	
Specific gravity		3.4	
Filler content		75	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	> 24	hrs
Shelf Life	≤ -20 °C	> 180	days

■ Cured Material Properties

Glass transition temperature	TMA	147	°C
	DMA	170	°C
Hardness	ShoreD	> D80	
Storage modulus/ 25°C	DMA	6	GPa
Coefficient of linear expansion	α _l	43	ppm
Volume resistivity	Four-point probe method	3 × 10 ⁻³	Ω · cm

DSC : SH DCS6220 25 – 250 °C (10 °C/min)

DMA : TA RSA-G2 10 – 250 °C (10 °C/min),
curing condition ; 150 °C × 1 hr

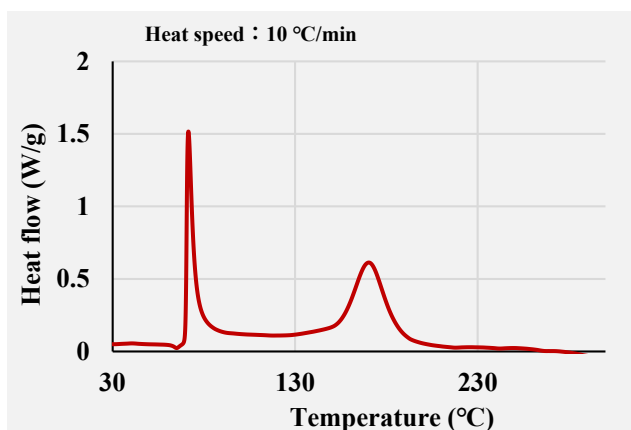
TMA : SH TMA/SS6100 10 – 150 °C (5 °C/min),
curing condition ; 150 °C × 1 hr

■ Recommended Curing Conditions

150 °C

15 min

■ Curing behavior (DSC curve)



■ Usage

【Storage】 Store frozen (below -20 °C)

【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.
Recommended defrosting time : Syringe ; 25 °C, 1 h or more.
Barrel ; 25 °C, 2 h or more.

【Curing】 When curing more than 1 g, please be careful of runaway reactions.

【Disposal】 Please refer to SDS for proper treatment.

【Others】 Please contact us at the following

株式会社 ADEKA

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